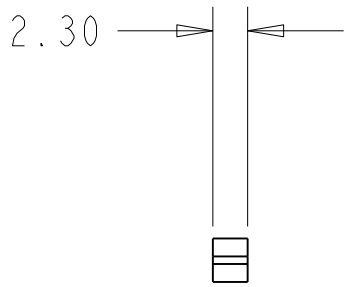
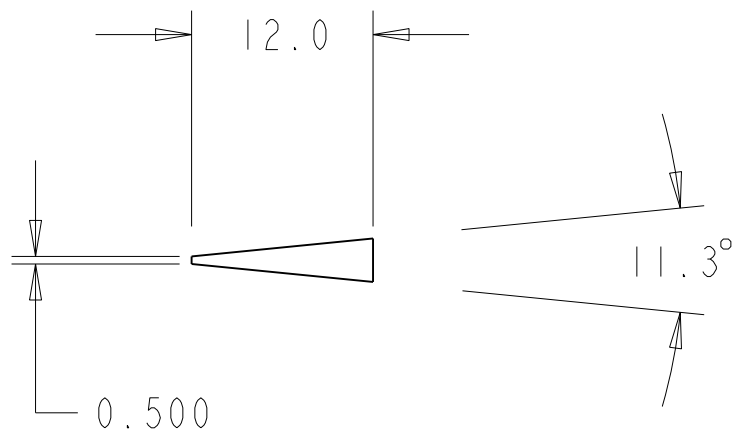
DWG. NO.	SIZE	REV.	SH.
21F3591		1	1





REV	DWG	CHK	DATE	CHANGES

DESCRIPTION	MATERIAL
	M55J CARBON-CARBON

UNLESS OTHERWISE SPECIFIED

TOLERANCES			
X.X ±0.1	FRAC. ±1/64	FINISH 125 (µin)	
X.XX ±0.01	Angles ±0.50°		
X.XXX ±0.001			

DO NOT SCALE PRINT

THREADS ARE CLASS 2
CHAMFER ENDS OF ALL SCREW TREADS 30°
CUT ROUND, 1.5 THREAD RELIEF ON MACHINED THREADS
BREAK EDGES .016 MAX. ON MACHINED WORK
REMOVE BURRS, WELD SPLATTER & LOOSE SCALE
IN ACCORDANCE WITH ASME Y14.5M & B46.1

SHOP ORDERS

ACCT NO.	SEE J.O.	NO. REQD	120	SER NO.	-
DEL TO	J WIRTH			DATE ISSD	-
SURFACE TREATMT				DATE REQD	-
IDENT METHOD	TAG				
PROJECT NUMBER	ATL-IP-ED-0035				
PROJECT NAME	US ATLAS SILICON SUBSYSTEM				
DWG BY	D UKEN			DATE	29-Jun-01
CHK BY	J WIRTH			DATE	18-FEB-01
APR BY	E ANDERSSEN			DATE	18-FEB-01

ERNEST ORLANDO LAWRENCE BERKELEY NATIONAL LABORATORY
UNIVERSITY OF CALIFORNIA - BERKELEY

ATLAS PIXEL DETECTOR
DISK SECTOR, MODULE LOCAL SUPPORT
WEDGE HARDPOINT, SECTOR FACING SUPPORT

MICROFILMED:	DWG. TYPE	SHOWN ON	SCALE: 2.000	DO NOT SCALE PRINTS
	PART	21F352	SHEET 1 OF 1	
PATENT CLEAR:	DESIGN ACCT. NO.	CATEGORY CODE	DWG. NO.	SIZE / REV.
	ON J.O.	AP6110	21F3591	1

Rev. 1/8/2001 ATLAS

Dwg. File: 21F359 Model File: 21F359